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Intel - 5SGXMA5N2F45C3N Datasheet



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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Details	
Product Status	Obsolete
Number of LABs/CLBs	185000
Number of Logic Elements/Cells	490000
Total RAM Bits	46080000
Number of I/O	840
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1932-BBGA, FCBGA
Supplier Device Package	1932-FBGA, FC (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxma5n2f45c3n

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Symbol	Description	Minimum	Maximum	Unit
V _{CCD_FPLL}	PLL digital power supply	-0.5	1.8	V
V _{CCA_FPLL}	PLL analog power supply	-0.5	3.4	V
VI	DC input voltage	-0.5	3.8	V
TJ	Operating junction temperature	-55	125	°C
T _{STG}	Storage temperature (No bias)	-65	150	°C
I _{OUT}	DC output current per pin	-25	40	mA

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices

Symbol	Description	Devices	Minimum	Maximum	Unit
V _{CCA_GXBL}	Transceiver channel PLL power supply (left side)	GX, GS, GT	-0.5	3.75	V
V _{CCA_GXBR}	Transceiver channel PLL power supply (right side)	GX, GS	-0.5	3.75	V
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	-0.5	3.75	V
V _{CCHIP_L}	Transceiver hard IP power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCHIP_R}	Transceiver hard IP power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCHSSI_R}	Transceiver PCS power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GXBL}	Receiver analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V _{CCT_GXBL}	Transmitter analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCT_GXBR}	Transmitter analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V _{CCL_GTBR}	Transmitter clock network power supply (right side)	GT	-0.5	1.35	V
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	-0.5	1.8	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	-0.5	1.8	V

Maximum Allowed Overshoot and Undershoot Voltage

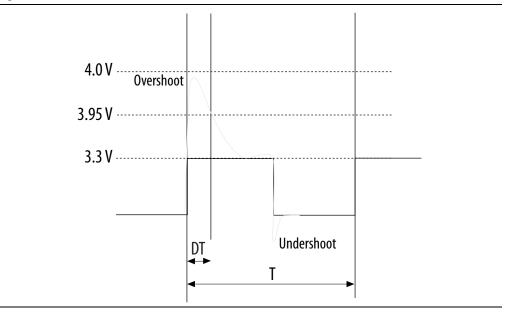
During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to -2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

Table 5 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle. For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

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Symbol	Description	Condition (V)	Overshoot Duration as % @ T _J = 100°C	Unit
		3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
Vi (AC)	AC input voltage	4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Table 5. Maximum Allowed Overshoot During Transitions

Figure 1. Stratix V Device Overshoot Duration



This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC}	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) ⁽³⁾	_	0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
VI (1)	I/O pre-driver (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply		2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply		1.71	1.8	1.89	V
V _{CCIO}	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	_	1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply	_	1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply	_	2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply	_	1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
VI	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	—	0	—	V _{CCIO}	V
т	Operating junction temperature	Commercial	0	—	85	°C
TJ	Operating junction temperature	Industrial	-40	_	100	°C

I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin leakage current specifications.

Table 9. I/	0 Pin Leakage	Current for Stratix 	/ Devices ⁽¹⁾
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Symbol	Description	Conditions	Min	Тур	Max	Unit
I _I	Input pin	$V_I = 0 V \text{ to } V_{CCIOMAX}$	-30	—	30	μA
I _{0Z}	Tri-stated I/O pin	$V_0 = 0 V \text{ to } V_{\text{CCIOMAX}}$	-30		30	μA

Note to Table 9:

(1) If $V_0 = V_{CCIO}$ to $V_{CCIOMax}$, 100 μ A of leakage current per I/O is expected.

Bus Hold Specifications

Table 10 lists the Stratix V device family bus hold specifications.

Table 10. Bus Hold Parameters for Stratix V Devices

			V _{CCIO}										
Parameter	Symbol	Conditions	1.2	2 V	1.	5 V	1.8	B V	2.	5 V	3.0	V	Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Low sustaining current	I _{SUSL}	V _{IN} > V _{IL} (maximum)	22.5	_	25.0	_	30.0	_	50.0	_	70.0	_	μA
High sustaining current	I _{SUSH}	V _{IN} < V _{IH} (minimum)	-22.5	_	-25.0	_	-30.0	_	-50.0	_	-70.0	_	μA
Low overdrive current	I _{odl}	$0V < V_{IN} < V_{CCIO}$	_	120	_	160	_	200	_	300	_	500	μA
High overdrive current	I _{odh}	$0V < V_{IN} < V_{CCIO}$		-120		-160	_	-200		-300	_	-500	μA
Bus-hold trip point	V _{trip}	_	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices ⁽¹⁾ (Part 1 of 2)

				Calibratio	n Accuracy		
Symbol	Description	Conditions	C1	C2,12	C3,I3, I3YY	C4,14	Unit
25-Ω R _S	Internal series termination with calibration (25- Ω setting)	V _{CCI0} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

				Calibratio	n Accuracy		
Symbol	Description	Conditions	C1	C2,12	C3,I3, I3YY	C4,14	Unit
50-Ω R _S	Internal series termination with calibration (50- Ω setting)	V _{CCI0} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%
34-Ω and 40-Ω R _S	Internal series termination with calibration (34- Ω and 40- Ω setting)	V _{CCI0} = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%
48-Ω, 60-Ω, 80-Ω, and 240-Ω R _S	Internal series termination with calibration (48- Ω , 60- Ω , 80- Ω , and 240- Ω setting)	V _{CCI0} = 1.2 V	±15	±15	±15	±15	%
50-Ω R _T	Internal parallel termination with calibration (50-Ω setting)	V _{CCIO} = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
20- $Ω$, 30- $Ω$, 40- $Ω$,60- $Ω$, and 120- $Ω$ R _T	Internal parallel termination with calibration ($20 \cdot \Omega$, $30 \cdot \Omega$, $40 \cdot \Omega$, $60 \cdot \Omega$, and $120 \cdot \Omega$ setting)	V _{CCI0} = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
60-Ω and 120-Ω R_T	Internal parallel termination with calibration (60- Ω and 120- Ω setting)	V _{CCI0} = 1.2	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{l} \textbf{25-}\Omega\\ \textbf{R}_{S_left_shift} \end{array}$	Internal left shift series termination with calibration (25- Ω R _{S_left_shift} setting)	V _{CCI0} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

Table 11. OCT Calibration Accurat	y Specifications for Stratix V Devices ⁽¹⁾ ((Part 2 of 2)
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Note to Table 11:

(1) OCT calibration accuracy is valid at the time of calibration only.

Table 12 lists the Stratix V OCT without calibration resistance to PVT changes.

			Re	1			
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit
25-Ω R, 50-Ω R _S	Internal series termination without calibration (25- Ω setting)	$V_{CCIO} = 3.0$ and 2.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25-Ω setting)	$V_{CCI0} = 1.8$ and 1.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25-Ω setting)	V _{CCI0} = 1.2 V	±35	±35	±50	±50	%

			Re					
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit	
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	$V_{CCIO} = 1.8$ and 1.5 V	±30	±30	±40	±40	%	
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCI0} = 1.2 V	±35	±35	±50	±50	%	
100-Ω R _D	Internal differential termination (100- Ω setting)	V _{CCPD} = 2.5 V	±25	±25	±25	±25	%	

Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 2 of 2)

Calibration accuracy for the calibrated series and parallel OCTs are applicable at the moment of calibration. When voltage and temperature conditions change after calibration, the tolerance may change.

OCT calibration is automatically performed at power-up for OCT-enabled I/Os. Table 13 lists the OCT variation with temperature and voltage after power-up calibration. Use Table 13 to determine the OCT variation after power-up calibration and Equation 1 to determine the OCT variation without recalibration.

Equation 1. OCT Variation Without Recalibration for Stratix V Devices (1), (2), (3), (4), (5), (6)

$$R_{OCT} \,=\, R_{SCAL} \Big(1 + \langle \frac{dR}{dT} \times \Delta T \rangle \pm \langle \frac{dR}{dV} \times \Delta V \rangle \Big)$$

Notes to Equation 1:

- (1) The R_{OCT} value shows the range of OCT resistance with the variation of temperature and V_{CCIO} .
- (2) R_{SCAL} is the OCT resistance value at power-up.
- (3) ΔT is the variation of temperature with respect to the temperature at power-up.
- (4) ΔV is the variation of voltage with respect to the V_{CCIO} at power-up.
- (5) dR/dT is the percentage change of R_{SCAL} with temperature.
- (6) dR/dV is the percentage change of $\mathsf{R}_{\mathsf{SCAL}}$ with voltage.

Table 13 lists the on-chip termination variation after power-up calibration.

Table 13.	OCT Variation after Power-U	Calibration for Stratix V Devices	(Part 1 of 2) ⁽¹⁾
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Symbol	Description	V _{CCIO} (V)	Typical	Unit
dR/dV		3.0	0.0297	
	OCT variation with voltage without recalibration	2.5	0.0344	
		1.8	0.0499	%/mV
		1.5	0.0744	
		1.2	0.1241	

Symbol	Description	V _{CCIO} (V)	Typical	Unit
dR/dT		3.0	0.189	
		2.5	0.208	
	OCT variation with temperature without recalibration	1.8	0.266	%/°C
		1.5	0.273	
		1.2	0.317	

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2)⁽¹⁾

Note to Table 13:

(1) Valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0° to 85°C.

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Description	Value	Unit	
C _{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF	
C _{IOLR}	Input capacitance on the left and right I/O pins	6	рF	
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	рF	

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15.	Hot Socketing Specifications for Stratix V Devices
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Symbol	Description	Maximum
I _{IOPIN (DC)}	DC current per I/O pin	300 μA
I _{IOPIN (AC)}	AC current per I/O pin	8 mA ⁽¹⁾
I _{XCVR-TX (DC)}	DC current per transceiver transmitter pin	100 mA
I _{XCVR-RX (DC)}	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{10PIN}| = C dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

1/0 Stondard		V _{ccio} (V)		V _{REF} (V)			V _Π (V)			
I/O Standard	Min Typ Max		Max	Min Typ		Max	Min	Тур	Max	
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	V _{REF} – 0.04	V _{REF}	V _{REF} + 0.04	
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V _{REF} – 0.04	V _{REF}	V _{REF} + 0.04	
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCI0}	0.5 * VCCIO	0.51 * V _{CCIO}	
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCI0}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCI0}	0.49 * V _{CCI0}	0.5 * VCCIO	0.51 * V _{CCIO}	
SSTL-12 Class I, II	1.14	1.20	1.26	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCI0}	0.5 * VCCIO	0.51 * V _{CCIO}	
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	_	V _{CCI0} /2	_	
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	_	V _{CCI0} /2	_	
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 * V _{CCIO}	0.5 * V _{CCIO}	0.53 * V _{CCIO}	—	V _{CCI0} /2		
HSUL-12	1.14	1.2	1.3	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	—	_	_	

Table 18. Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Stratix V Device	es
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Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices	(Part 1 of 2)
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I/O Standard	V _{IL(D(}	_{:)} (V)	V _{IH(D}	_{C)} (V)	V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{ol} (V)	V _{oh} (V)	L (mA)	I _{oh}
ijo Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	I _{ol} (mA)	(mÅ)
SSTL-2 Class I	-0.3	V _{REF} – 0.15	V _{REF} + 0.15	V _{CCI0} + 0.3	V _{REF} – 0.31	V _{REF} + 0.31	V _{TT} – 0.608	V _{TT} + 0.608	8.1	-8.1
SSTL-2 Class II	-0.3	V _{REF} – 0.15	V _{REF} + 0.15	V _{CCI0} + 0.3	V _{REF} – 0.31	V _{REF} + 0.31	V _{TT} – 0.81	V _{TT} + 0.81	16.2	-16.2
SSTL-18 Class I	-0.3	V _{REF} – 0.125	V _{REF} + 0.125	V _{CCI0} + 0.3	V _{REF} – 0.25	V _{REF} + 0.25	V _{TT} – 0.603	V _{TT} + 0.603	6.7	-6.7
SSTL-18 Class II	-0.3	V _{REF} – 0.125	V _{REF} + 0.125	V _{CCI0} + 0.3	V _{REF} – 0.25	V _{REF} + 0.25	0.28	V _{CCI0} – 0.28	13.4	-13.4
SSTL-15 Class I		V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} – 0.175	V _{REF} + 0.175	0.2 * V _{CCI0}	0.8 * V _{CCI0}	8	-8
SSTL-15 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} – 0.175	V _{REF} + 0.175	0.2 * V _{CCI0}	0.8 * V _{CCI0}	16	-16
SSTL-135 Class I, II		V _{REF} – 0.09	V _{REF} + 0.09	_	V _{REF} – 0.16	V _{REF} + 0.16	0.2 * V _{CCI0}	0.8 * V _{CCI0}	_	_
SSTL-125 Class I, II		V _{REF} – 0.85	V _{REF} + 0.85	_	V _{REF} – 0.15	V _{REF} + 0.15	0.2 * V _{CCI0}	0.8 * V _{CCI0}	_	_
SSTL-12 Class I, II		V _{REF} – 0.1	V _{REF} + 0.1		V _{REF} – 0.15	V _{REF} + 0.15	0.2 * V _{CCIO}	0.8 * V _{CCIO}		_

Symbol/ Description		Trai	Transceiver Speed Grade 1		Transceiver Speed Grade 2		Transceiver Speed Grade 3			Unit	
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} (16)	_			10		—	10	—		10	μs

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 7 of 7)

Notes to Table 23:

(2) The reference clock common mode voltage is equal to the V_{CCR_GXB} power supply level.

(3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.

- (4) This supply follows VCCR_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t_{LTD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high.
- (13) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) $t_{LTR_LTD_manual}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15) $t_{pll_powerdown}$ is the PLL powerdown minimum pulse width.
- (16) t_{pll lock} is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (19) For ES devices, R_{BEF} is 2000 $\Omega \pm 1\%$.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

⁽¹⁾ Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the Stratix V Device Overview.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 4 of 5) ⁽¹⁾
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Symbol/	Conditions		Transceive peed Grade			Fransceive Deed Grade		Unit	
Description		Min	Тур	Max	Min	Тур	Max		
Data rate	GT channels	19,600		28,050	19,600		25,780	Mbps	
Differential on-chip	GT channels		100	_		100		Ω	
termination resistors	GX channels		1	1	(8)		11		
	GT channels		500	_		500	—	mV	
V_{OCM} (AC coupled)	GX channels		1	1	(8)		11		
Dies/Fall times	GT channels	_	15	_		15	—	ps	
Rise/Fall time	GX channels				(8)		1		
Intra-differential pair skew	GX channels	(8)							
Intra-transceiver block transmitter channel-to- channel skew	GX channels		(8)						
Inter-transceiver block transmitter channel-to- channel skew	GX channels				(8)				
CMU PLL	· · · · · ·								
Supported Data Range	—	600	—	12500	600	—	8500	Mbps	
t _{pll_powerdown} (13)	—	1	—	—	1	_	—	μs	
t _{pll_lock} ⁽¹⁴⁾	—	_	—	10	_	_	10	μs	
ATX PLL									
	VCO post- divider L=2	8000	_	12500	8000	_	8500	Mbps	
	L=4	4000		6600	4000	_	6600	Mbps	
Supported Data Rate	L=8	2000	—	3300	2000	-	3300	Mbps	
Range for GX Channels	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	Mbps	
Supported Data Rate Range for GT Channels	VCO post- divider L=2	9800	_	14025	9800	_	12890	Mbps	
t _{pll_powerdown} ⁽¹³⁾	—	1	—	—	1	—	—	μs	
t _{pll_lock} ⁽¹⁴⁾	—		—	10	—	—	10	μs	
fPLL						-	· ·		
Supported Data Range	_	600		3250/ 3.125 ⁽²³⁾	600	_	3250/ 3.125 ⁽²³⁾	Mbps	
t _{pll_powerdown} (13)		1	_		1			μs	

Table 29 shows the V_{OD} settings for the GT channel.

Table 29.	Typical Von Setting	g for GT Channel, T	EX Termination = 100 Ω
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Symbol	V _{OD} Setting	V _{op} Value (mV)
	0	0
	1	200
\mathbf{V}_{0D} differential peak to peak typical (1)	2	400
VOD unicicilitat peak to peak typical (*)	3	600
	4	800
	5	1000

Note:

(1) Refer to Figure 4.

Figure 4 shows the differential transmitter output waveform.



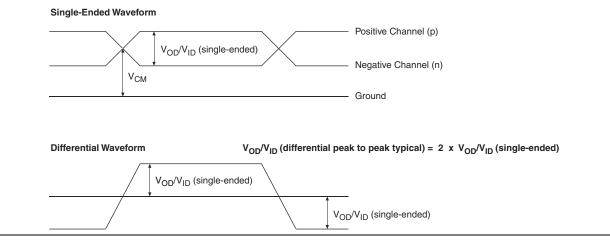


Figure 5 shows the Stratix V AC gain curves for GT channels.

Figure 5. AC Gain Curves for GT Channels

Figure 6 shows the Stratix V DC gain curves for GT channels.

Figure 6. DC Gain Curves for GT Channels

Transceiver Characterization

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

Clock Tree Specifications

Table 30 lists the clock tree specifications for Stratix V devices.

Table 30. Clock Tree Performance for Stratix V Devices (1)

		Performance						
Symbol	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	C4, I4	Unit				
Global and Regional Clock	717	650	580	MHz				
Periphery Clock	550	500	500	MHz				

Note to Table 30:

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

Table 31. PLL Specifications for Stratix V Devices (Part 3 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
f _{RES}	Resolution of VCO frequency ($f_{INPFD} = 100 \text{ MHz}$)	390625	5.96	0.023	Hz

Notes to Table 31:

(1) This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

(2) This specification is limited by the lower of the two: I/O f_{MAX} or f_{OUT} of the PLL.

- (3) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source < 120 ps.
- (4) f_{REF} is fIN/N when N = 1.
- (5) Peak-to-peak jitter with a probability level of 10⁻¹² (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Table 44 on page 52.
- (6) The cascaded PLL specification is only applicable with the following condition: a. Upstream PLL: 0.59Mhz ≤ Upstream PLL BW < 1 MHz b. Downstream PLL: Downstream PLL BW > 2 MHz
- (7) High bandwidth PLL settings are not supported in external feedback mode.
- (8) The external memory interface clock output jitter specifications use a different measurement method, which is available in Table 42 on page 50.
- (9) The VCO frequency reported by the Quartus II software in the PLL Usage Summary section of the compilation report takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.
- (10) This specification only covers fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05 0.95 must be \geq 1000 MHz, while f_{VCO} for fractional value range 0.20 0.80 must be \geq 1200 MHz.
- (11) This specification only covered fractional PLL for low bandwidth. The f_{VC0} for fractional value range 0.05-0.95 must be \geq 1000 MHz.
- (12) This specification only covered fractional PLL for low bandwidth. The f_{VC0} for fractional value range 0.20-0.80 must be \geq 1200 MHz.

DSP Block Specifications

Table 32 lists the Stratix V DSP block performance specifications.

	Peformance							
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit
		Modes ι	ising one	DSP				4
Three 9 x 9	600	600	600	480	480	420	420	MHz
One 18 x 18	600	600	600	480	480	420	400	MHz
Two partial 18 x 18 (or 16 x 16)	600	600	600	480	480	420	400	MHz
One 27 x 27	500	500	500	400	400	350	350	MHz
One 36 x 18	500	500	500	400	400	350	350	MHz
One sum of two 18 x 18(One sum of 2 16 x 16)	500	500	500	400	400	350	350	MHz
One sum of square	500	500	500	400	400	350	350	MHz
One 18 x 18 plus 36 (a x b) + c	500	500	500	400	400	350	350	MHz
		Modes u	sing two l	DSPs	1		•	1
Three 18 x 18	500	500	500	400	400	350	350	MHz
One sum of four 18 x 18	475	475	475	380	380	300	300	MHz
One sum of two 27 x 27	465	465	450	380	380	300	290	MHz
One sum of two 36 x 18	475	475	475	380	380	300	300	MHz
One complex 18 x 18	500	500	500	400	400	350	350	MHz
One 36 x 36	475	475	475	380	380	300	300	MHz

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 1 of 2)

		Resour	ces Used	Performance							
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, 12L	13, 13L, 13YY	14	Unit
	Single-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	525	525	455	400	525	455	400	MHz
M20K Block	Simple dual-port with ECC enabled, 512 × 32	0	1	450	450	400	350	450	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	600	600	500	450	600	500	450	MHz
	True dual port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	ROM, all supported widths	0	1	700	700	650	550	700	500	450	MHz

Table 33. Memory Block Performance Specifications for Stratix V Devices ^{(1), (2)} (Part 2 of 2)

Notes to Table 33:

(1) To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50**% output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.

(2) When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in F_{MAX}.

(3) The F_{MAX} specification is only achievable with Fitter options, MLAB Implementation In 16-Bit Deep Mode enabled.

Temperature Sensing Diode Specifications

Table 34 lists the internal TSD specification.

Table 34. Internal Temperature Sensing Diode Specification

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
–40°C to 100°C	±8°C	No	1 MHz, 500 KHz	< 100 ms	8 bits	8 bits

Table 35 lists the specifications for the Stratix V external temperature sensing diode.

Description	Min	Тур	Max	Unit
I _{bias} , diode source current	8	—	200	μA
V _{bias,} voltage across diode	0.3	—	0.9	V
Series resistance		—	< 1	Ω
Diode ideality factor	1.006	1.008	1.010	

Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

Table 50. FPP Timing Parameters for Stratix V Devices (1)

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μS
t _{status}	nSTATUS low pulse width	268	1,506 ⁽²⁾	μS
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽³⁾	μS
t _{CF2CK} (6)	nCONFIG high to first rising edge on DCLK	1,506	_	μS
t _{ST2CK} ⁽⁶⁾	nSTATUS high to first rising edge of DCLK	2	_	μS
t _{DSU}	DATA [] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA [] hold time after rising edge on DCLK	0	_	ns
t _{CH}	DCLK high time	$0.45\times1/f_{MAX}$	—	S
t _{CL}	DCLK low time	$0.45\times1/f_{MAX}$	—	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	—	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	—	100	MHz
t _{CD2UM}	CONF_DONE high to user mode ⁽⁴⁾	175	437	μS
+	CONF_DONE high to CLKUSR enabled	4 × maximum		
t _{CD2CU}		DCLK period		_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$\begin{array}{c} t_{\text{CD2CU}} + \\ (8576 \times \text{CLKUSR} \\ \text{period}) \ ^{(5)} \end{array}$	_	_

Notes to Table 50:

(1) Use these timing parameters when the decompression and design security features are disabled.

(2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

(3) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

- (4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.
- (5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is more than 1.

Symbol	Parameter	Minimum	Maximum	Units
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	—
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{cd2cu} + (8576 × clkusr period)	_	—

Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices ^{(1), (2)} (Part 2 of 2)

Notes to Table 53:

(1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.

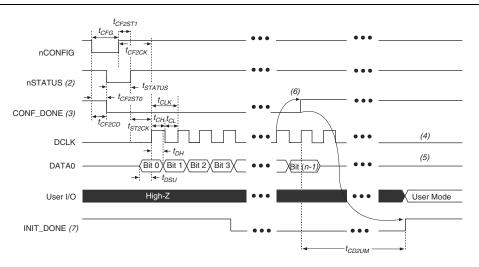
(2) t_{CF2CD}, t_{CF2ST0}, t_{CF2ST0}, t_{CF6}, t_{STATUS}, and t_{CF2ST1} timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.

(3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform ⁽¹⁾



Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds <code>nSTATUS</code> low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions
G		
Н	_	_
Ι		
J	J JTAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus). JTAG Timing Specifications: TMS TDI t_{JCP} t_{JCH} t_{JCH} t_{JPCO} t_{JPCO} t_{JPXZ} TDO t_{JPXZ} t_{JPXZ}
K L M N O	_	_
Ρ	PLL Specifications	Diagram of PLL Specifications (1)
Q		_
	1	

Letter	Subject	Definitions
	V _{CM(DC)}	DC common mode input voltage.
	V _{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.
	V _{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	V _{DIF(AC)}	AC differential input voltage—Minimum AC input differential voltage required for switching.
	V _{DIF(DC)}	DC differential input voltage— Minimum DC input differential voltage required for switching.
	V _{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	V _{IH(AC)}	High-level AC input voltage
	V _{IH(DC)}	High-level DC input voltage
V	V _{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	V _{IL(AC)}	Low-level AC input voltage
	V _{IL(DC)}	Low-level DC input voltage
	V _{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.
	V _{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
	V _{SWING}	Differential input voltage
	V _X	Input differential cross point voltage
	V _{OX}	Output differential cross point voltage
W	W	High-speed I/O block—clock boost factor
X		
Y	_	_
Z		

Table 60. Glossary (Part 4 of 4)